

Datasheet revision 1.9 www.chipquik.com

Liquid Flux No-Clean in 10ml (0.34oz) Pen w/tip

Product Highlights

A liquid flux that is non-flammable
No-Clean
Water-Based, leaves no residues
VOC Free, Halide Free, Rosin Free
Ideal for all rework, solder, and de-solder applications
Excellent wetting
Easily cleaned with isopropyl alcohol (IPA)
Can be used with Leaded and Lead-Free applications



Specifications

Flux Type: No-Clean Liquid Flux (for Leaded and Lead-Free applications)

Flux Classification: ORL0
VOC Content: VOC Free
Acid Number: 38.0
Total Solids: 4.0%
Specific Gravity: 1.01
Packaging: 10ml Pen

RoHS 3 and REACH compliant

Shelf Life: Refrigerated >24 months, Unrefrigerated >24 months

Dispensing

Gently press tip into work piece (depress tip) to dispense.

Storage and Handling

Store refrigerated or at room temperature 3-25°C (37-77°F). The liquid flux can be allowed to freeze. Freezing will not degrade this product. Allow 4 hours for flux to reach an operating temperature of 20-25°C (68-77°F) before use.

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

Cleaning

This is a no-clean liquid flux, post-use cleaning is not required.

Test Results

| Test J-STD-004 or other requirements as stated | Test Requirement | Result |
|--------------------------------------------------------|-------------------------------------------------------|----------------------------------------------------------------------------------------------------|
| Copper Mirror | IPC-TM-650: 2.3.32 | L: No breakthrough |
| Corrosion | IPC-TM-650: 2.6.15 | L: No corrosion |
| Quantitative Halides | IPC-TM-650: 2.3.28.1 | L: <0.05% |
| Electrochemical Migration | IPC-TM-650: 2.6.14.1 | L: <1 decade drop (No-clean) |
| Surface Insulation Resistance 85°C, 85% RH @ 168 Hours | IPC-TM-650: 2.6.3.7 | L: ≥100MΩ (No-clean) |
| REACH Compliance | Articles 33 and 67 of Regulation (EC) No 1907/2006 | Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials |

Conforms to the following Industry Standards:

J-STD-004B, Amendment 1 (Solder Fluxes):

RoHS 3 Directive (EU) 2015/863:

Yes